

PLASTRON	0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION	Rev.	Document No.	SHEET
		A	WI-RD-S004	Page1 of 5

1. SCOPE

This product specification contains the test method, the general performance and property for 0.8 Pitch Board To Board connector

2. General items:

2.1 Application

This specification applies to the 0.8 Pitch Board To Board connector

2.2 Operating Temperature Range: -40~105 °C

2.3 Storage Temperature Range: -40~85 °C

3. PROPERTY

3.1 MATERIALS

Item	Standard
Housing	High Temperature Thermoplastic , UL 94V-0
Contact	Copper Alloy, Gold plating

3.2 RATINGS

Item	Standard
Current Rating	0.5 A AC/DC Max.
Voltage Rating	50V AC/DC
Ambient Temperature Range	-40℃ ~ +105℃
Storage Temperature Range	-40℃ ~ +85℃
Ambient ` Range	95 % R.H. Max.

PLASTRON	0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION	Rev.	Document No.	SHEET
		A	WI-RD-S004	Page2 of 5

4. Test Methods and Requirements:

4.1 Electrical Performance

Item	Test Item	Standard	Test Condition
4.1.1	Contact Resistance	It should be tested in accordance. (EIA-364-23)	50 mΩ max. Initial
4.1.2	Insulation Resistance	Apply a voltage of AC 500V for 2 minutes between adjacent terminals and measure. (EIA-364-21C)	100 MΩ min. Initial 50 MΩ min. Final
4.1.3	Dielectric Withstanding Voltage	Apply a voltage of AC 500V for 60±5s to between adjacent terminals.	There must be no breakdown.

4.2 Mechanical Performance:

4.2.1	Contact Retention force	Pull connectors at maximum rate of 25mm/minute.	200 grams min./per contact
4.2.2	Insertion force	Plug insert into socket shell be an alignment at a constant speed of 25mm/minute.	150gf Max per contact
4.2.3	Withdrawal force	Plug pull out socket shell be an alignment at a constant speed of 25mm/minute	25gf Min per contact
4.2.4	Durability	EIA-364-09C Connector shall be subjected to 30cycles of Insertion and withdrawal	50mΩ max. initial 70 mΩ max. Final

PLASTRON	0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION	Rev.	Document No.	SHEET
		A	WI-RD-S004	Page3 of 5

4.2.5	Vibration	10-55-10 Hz/min. Amplitude: 1.52mm Period: 2 hours for each direction X,Y,Z axis. (EIA-364-28E)	No electrical discontinuity greater than 1 microseconds shall occur.
4.2.6	Drop	76cm Height one carton 6-sydes random dropping.	[Appearance] No abnormality [Function] OK

4.3 Environmental Performance:

4.3.1	Thermal shock	EIA-364-32C, Condition I. One cycle consists of: -55°C for 30 minutes/+85°C for 30 minutes. Times of cycle: 5 cycles.	See Note 50mΩ max. initial 70 mΩ max Final
4.3.2	Humidity	EIA-364-31B, Method II, Condition A Temperature: 40 ±2°C Humidity: 90 ~ 95 % (RH) Period: 96 hours	See Note 50mΩ max. Initial 70 mΩ max Final
4.3.3	Salt Spray	EIA-364-26B, Condition A. Temperature: 35±2°C , Density 5% in weight. Period24 hours	50mΩ max. initial 70 mΩ max Final

4.4 Others

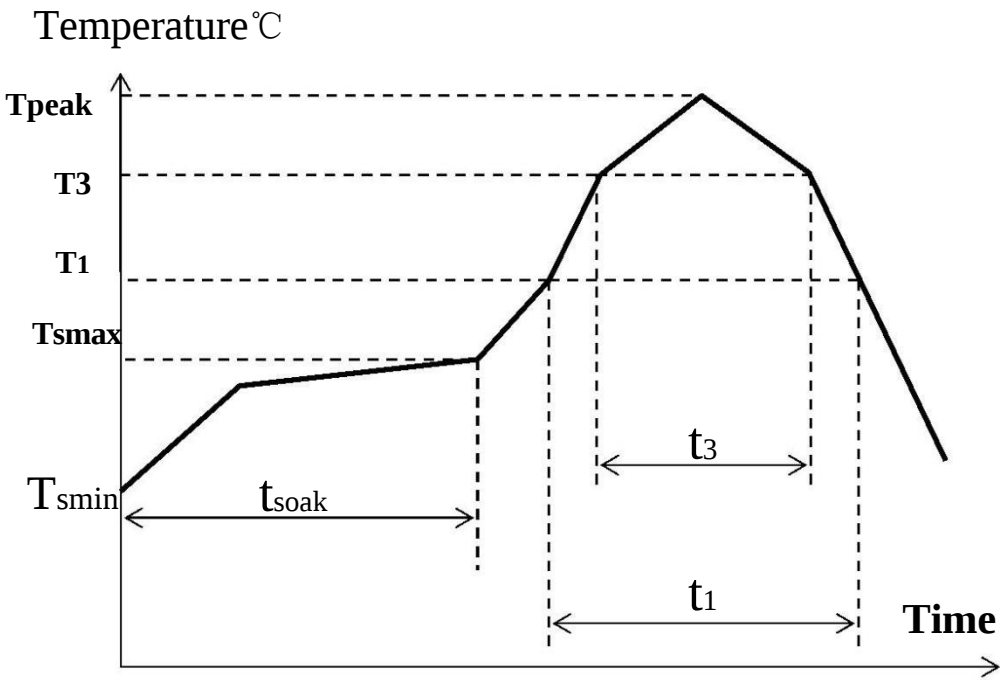
4.4.1	Solder ability	EIA-364-52 Temperature: 245+/-5°C,3~5sec	See Note 95%min
4.4.2	Temperature Life	EIA-364-17A, method A Condition 4. Temperature : 105 ± 2 °C Period250 hours	See Note 70 mΩ max Final

NOTE: Shall meet visual requirements , show no physical damages.

PLASTRON	0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION	Rev.	Document No.	SHEET
		A	WI-RD-S004	Page4 of 5

5. Reflow Profile for soldering heat resistance testing

Reflow Profile for soldering heat resistance testing		
Parameter	Mark	Major parts
Speed of temperature-raising		Not raise over 3℃ for each second
Temperature Min (Ts min)	Ts min	150℃
Temperature Max (Ts max)	Ts max	200℃
Time (ts min to ts max)	Ts	2~3minutes
Time of temperature over 217℃	t 1	60~150seconds
At the reflow area	t 3 T3	20~40 seconds (t 3) (T3)
At the highest temperature	T peak	260(+0/-5℃)
Speed of temperature-decreasing		Not decrease over 6℃ for each second
Time from 25℃ to highest temperature		Not over 8 minutes



SMT TYPE Re-flow profile for soldering heat(Lead free)

